

1200V 40A Trench and Field Stop IGBT

DESCRIPTION :

- High ruggedness performance
- High speed switching
- · Low collector to emitter saturation voltage
- · Easy parallel switching capability
- · RoHS compliant.

TYPICAL APPLICATIONS :

- Welding machines
- UPS applications
- Solar inverters

IGBT

MAXIMUM RATINGS (Tvj=25°C unless otherwise specified)

Characteristic	Condition	Symbol	Value	Unit
Collector-Emitter Voltage		V _{CES}	1200	V
Continuous collector current	Tc=25℃ Tc=100℃	I _C	80 40	Α
Pulsed collector current	t_P limited by Tvjmax	I _{CM}	160	А
Gate emitter voltage		V _{GE}	±20	V
Power dissipation	Tc=25℃ Tc=100℃	P _{tot}	681 340	W
Operating junction temperature range		Tvj	-40~+175	°C
Storage temperature		T _{STG}	-55~+150	°C

THERMAL CHARACTERISTICS

Characteristic	Condition	Symbol	Max.	Unit
IGBT thermal resistance, junction - case		R _{th(j-C)}	0.22	K/W
Diode thermal resistance, junction - case		$R_{th(j-C)}$	0.48	K/W
Thermal resistance, junction - ambient		$R_{\text{th}(j-A)}$	40	K/W



TO-247

ELECTRICAL CHARATERISTICS

Characteristic	Symbol	Min.	Тур.	Max.	Unit
Collector-emitter cut-off current VCE=1200V, VGE=0V Tvj=25 $^\circ$ C	I _{CES}			100	uA
Gate-emitter leakage current VCE=0V, VGE=±20V Tvj=25°C	I _{GES}			±100	nA
Gate-Emitter threshold voltage IC=1.0mA, VGE= VCE Tvj=25℃	$V_{GE(th)}$	5.0	6.0	7.0	V
Collector-Emitter saturation voltage VGE=15V, IC=40A Tvj=25℃ VGE=15V, IC=40A Tvj=175℃	$V_{CE(SAT)}$		1.9 2.2		V
Input capacitance f=1MHz, VCE=30 V, VGE=0 V Tvj=25℃	C _{ies}		9900		pF
Output capacitance f=1MHz, VCE=30 V, VGE=0 V Tvj=25℃	C _{oes}		189		pF
Reverse transfer capacitance f=1MHz, VCE=30 V, VGE=0 V Tvj=25 $^\circ$ C	C _{res}		40		pF
Gate charge IC = 40A, VGE = 15 V,VCC =960V Tvj=25 $^\circ$ C	Q _G		263		nC
Turn-on delay time IC=40A, VCC=600 V Tvj=25℃ VGE=0/15 V, RG=10Ω Tvj=175℃ (inductive load)	td _(ON)		85 76		ns
Rise time IC=40A, VCC=600 V Tvj=25℃ VGE=0/15 V, RG=10 Ω Tvj=175℃ (inductive load)	tr		76 75		ns
Turn-off delay time IC=40A, VCC=600 V Tvj=25℃ VGE=0/15 V, RG=10Ω Tvj=175℃ (inductive load)	td _(OFF)		307 360		ns
Fall time IC=40A, VCC=600 V Tvj=25℃ VGE=0/15 V, RG=10Ω Tvj=175℃ (inductive load)	tf		69 149		ns
Turn-on energy IC=40A, VCC=600 V Tvj=25℃ VGE=0/15 V, RG=10 Ω Tvj=175℃ (inductive load)	E _(ON)		2.5 2.9		mJ

Turn-off energy loss per pulse IC=40A, VCC=600 V Tvj=25°C VGE=0/15 V, RG=10 Ω Tvj=175°C (inductive load)	E _(OFF)		1.4 2.6		mJ	
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Diode

MAXIMUM RATINGS (Tvj=25°C unless otherwise specified)

Characteristic	Condition	Symbol	Value	Unit
Repetitive peak reverse voltage	Tvj=25℃	V _{RRM}	1200	V
Continuous forward current	Tc=100℃	I _F	40	А
Diode maximum current	t_P limited by Tvj max	I _{FM}	160	А

ELECTRICAL CHARATERISTICS

Characteristic	Symbol	Min.	Тур.	Max.	Unit
Forward voltage IF=40A, Tvj=25℃ IF=40A, Tvj=175℃	V _F		2.0 1.6		v
Reverse Recovered Time IF=40 A, Tvj=25℃ -diF/dt =750A/µs Tvj=175℃ VR=600 V	T _{rr}		175 285		ns
Peak reverse recovery current IF=40 A, Tvj=25℃ -diF/dt =750A/µs Tvj=175℃ VR=600 V	I _{RRM}		24 37		A
Reverse Recovered charge IF=40 A, Tvj=25℃ -diF/dt =750A/µs Tvj=175℃ VR=600 V	Q _{rr}		2000 5500		nC

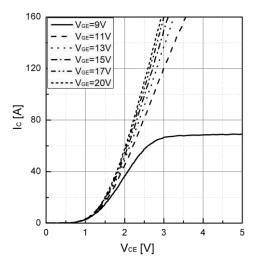


Figure 1. Typical output characteristics (Tvj=25 $^{\circ}$ C)

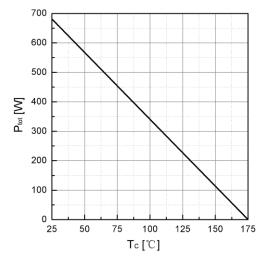


Figure 3. Power dissipation as a function of TC

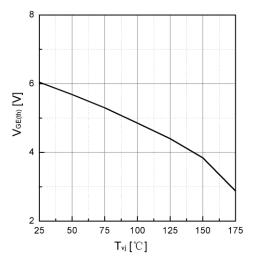


Figure 5. Typical VGE(th) as a function of Tvj ($I_C=1mA$)

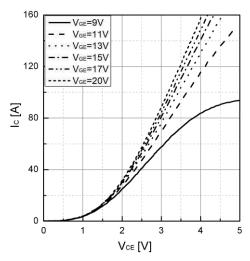


Figure 2. Typical output characteristics (Tvj=175°C)

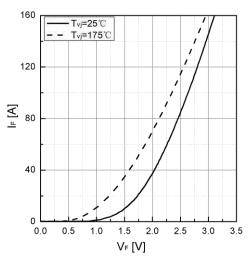


Figure 4. Typical IF as a function of VF

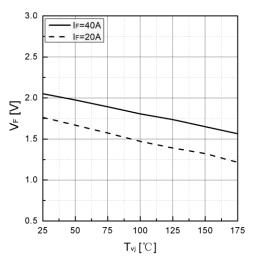


Figure 6. Typical VF as a function of Tvj

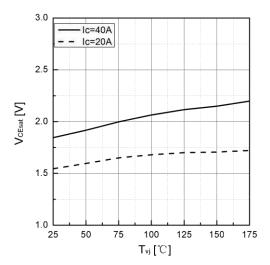


Figure 7. Typical VCEsat as a function of Tvj

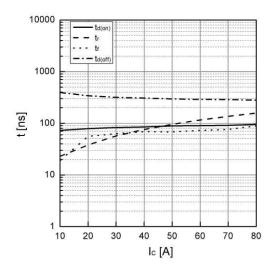


Figure 9. Typical switching times as a function of IC

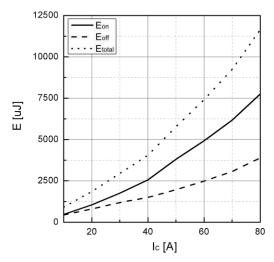


Figure 11. Typical switching energy losses as a function of IC

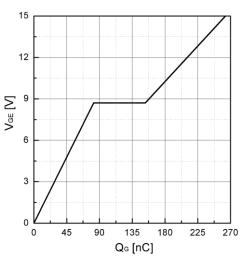


Figure 8. Typical Gate charge

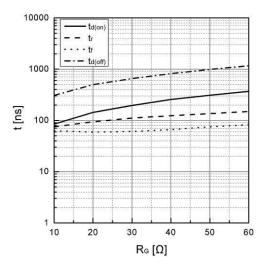


Figure 10. Typical switching times as a function of RG

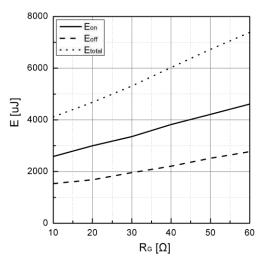


Figure 12. Typical switching energy losses as a function of RG

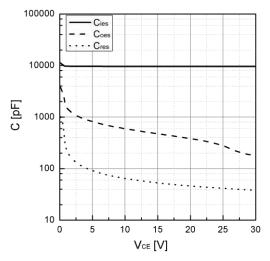


Figure 13. Typical capacitance as a function of VCE (f=1Mhz, VGE=0V)

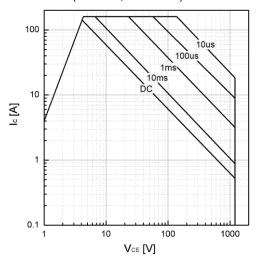


Figure 15. Safe operating area

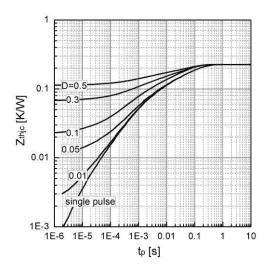
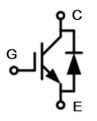
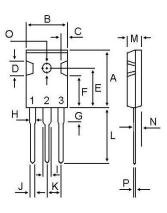


Figure 14. Transient thermal impedance, IGBT

Circuit diagram



Package outlines : Dimensions in (mm)



DIM	MILLIMETERS			
DIM	MIN	MAX		
A	20.80	21.80		
В	15.38	16.20		
С	1.90	2.70		
D	5.10	6.10		
E	14.50	15.50		
F	11.20	13.20		
G	3.75	4.35		
Н	1.90	2.30		
I	2.90	3.30		
J	1.00	1.40		
K	5.26	5.66		
L	19.50	20.50		
M	4.68	5.36		
N	2.30	2.60		
0	3.45	3.85		
P	0.48	0.72		



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